Amendments to the Specification:

Please replace the paragraph on page 4, line 18, with the following redlined paragraph:

Figures 1, 2A, and 2B show a base power module 10, generally comprising: a lead frame or housing 12, an integrated cold plate 14 attached to the housing 12 via bushings 15, a DC bus 16, an AC bus 18; and power semiconductor devices 20 electrically coupled between the DC bus 16 and AC bus 18, forming a high side ~~20a~~20b and a low side ~~20b~~20a of the power module 10. The base power module 10 may further include one or more gate drivers 22 for driving some of the power semiconductor devices 20.

Please replace the paragraph beginning on page 4, line 25, with the following redlined paragraph:

Two sets of DC bus terminals 24, 26 extend out of the housing 12. In some applications one set of DC bus terminals ~~24~~26 is electrically coupled to a positive voltage or high side of a power source or load and the other set of DC bus terminals ~~26~~24 is electrically coupled to a negative voltage or low side of the power source or load. In other applications, the DC bus terminals 24, 26 are electrically coupled to respective DC bus terminals 24, 26 on another power module. A set of AC phase terminals comprises three pairs of AC bus phase terminals 28a, 28b, 30a, 30b, 32a, 32b, extending out of the housing 12. As discussed in detail below, in some applications, one pair of AC phase terminals is coupled to a respective phase (A, B, C) of a three phase power source or load. In other applications, some of the AC phase terminals are interconnected across or between the pairs, and coupled to power sources or loads.

Please replace the paragraph on page 5, line 15, with the following redlined paragraph:

The integrated cold plate 14 comprises a metal base plate 39, a direct copper bonded (DCB) substrate 40 which is attached to the metal base plate 39 by a solder layer 41. A cooling header 42 includesing a number of cooling structures such as fins 42a, one or more fluid

channels 42b, and a fluid inlet 42c and a fluid outlet 42d for providing fluid connection flow to and from the fluid channels 42b, respectively.

Please replace the paragraph beginning on page 6, line 18, with the following redlined paragraph:

The DC bus 16 comprises a pair of L-shaped or vertical DC bus bars 34a, 36a. The upper legs of the L-shaped DC bus bars 34a, 36a are parallel and spaced from one another by the bus bar insulation 38. The lower legs of the L-shaped DC bus bars 34a, 36a are parallel with respect to the substrate 40 to permit wire bonding to appropriate portions of the substrate. For example, the negative DC bus bar 34a may be wire bonded to the emitter plating 43a of the low side, while the positive DC bus bar 36a may be wire bonded to the collector plating 44b of the high side. The emitters of the IGBTs 48 and anodes of the diodes 50 may be wire bonded to the respective emitter plating 43a, 43b. Wire bonding in combination with the rigid structure of the DC bus 16 and housing 12 may also eliminate the need for a hard potting compound typically used to provide rigidity to protect solder interfaces. For low cost, the copper layers 40a and 40c may be nickel finished or aluminum clad, although gold or palladium may be employed at the risk of incurring higher manufacturing costs.

Please replace the paragraph on page 10, line 17, with the following redlined paragraph:

Figures 6-10 illustrate tri-level inverters that take advantage, *inter alia*, of the inclusion of two terminals per phase in the design of the base power module 10. This approach reduces the size and cost over prior tri-level inverters which employ two separate bi-level modules for each phase, requiring fairly complex external coupling schemes.